

Specification for

**Harmonized system of
quality assessment for
electronic
components —
Semiconductor
devices —
Integrated circuits —
Blank detail
specification —**

**Bipolar monolithic digital integrated
circuit gates (excluding uncommitted
logic arrays)**

Amendments issued since publication

Amd. No.	Date	Comments

Contents

	Page
National foreword	ii
Introduction	1
1 Marking and ordering information	2
2 Application related description	3
3 Specification of the function	3
4 Limiting values (absolute maximum rating system)	3
5 Operating conditions (within the specified operating temperature range)	4
6 Electrical characteristics	4
7 Programming	6
8 Mechanical and climate ratings, characteristics and data	6
9 Additional information	6
10 Screening (if required)	7
11 Quality assessment procedures	7
12 Structural similarity procedures	7
13 Test conditionS and inspection requirements	7
4Additional measurement method	11
Table I — Group A (see note 6) <i>Lot-by-lot</i>	8
Table II — Group B <i>Lot-by-lot</i>	9
Table III — Group C <i>Periodic</i>	10
Table IV — Group D <i>Qualification approval tests</i>	11

National foreword

This British Standard has been prepared under the direction of the Electronic Components Standards Policy Committee, ECL/-. It is identical with IEC Publication 748-2-1 [QC 790132] *Semiconductor devices. Integrated circuits. Part 2: Digital integrated circuits. Section 1: Blank detail specification for bipolar monolithic digital integrated circuit gates [excluding uncommitted logic arrays]* published by the International Electrotechnical Commission [IEC] and is a harmonized specification with the IECQ system of quality assessment for electronic components.

This blank detail specification is one of a series of blank detail specifications for semiconductor devices to be used with BS QC 700000 “*Generic specification for discrete devices and integrated circuits*”.

Cross-references

International Standard ^a	Corresponding British Standard
IEC 68-2-17	BS 2011 <i>Environmental testing</i> Part 2.1 Q:1981 <i>Test Q. Sealing</i> [Identical]
IEC 617-12	BS 3939 <i>Guide for graphical symbols for electrical power, telecommunications and electronics diagrams</i> Part 12:1985 <i>Binary logic elements</i> [Identical]
IEC 747-10	BS QC 700000:1991 <i>Harmonized system of quality assessment for electronic components. Semiconductor devices. Generic specification for discrete devices and integrated circuits</i> [Identical]
	BS 6493 <i>Semiconductor devices</i> Part 2: <i>Integrated circuits</i>
IEC 748-1	Section 2.1:1985 <i>General</i> [Identical]
IEC 748-2	Section 2.2:1986 <i>Recommendations for digital integrated circuits</i> [Identical]
IEC 748-11	BS QC 790100:1991 <i>Harmonized system of quality assessment for electronic components. Semiconductor devices. Sectional specification for semiconductor integrated circuits excluding hybrid circuits</i> [Identical]
IEC 749	BS 6493 <i>Semiconductor devices</i> Part 3:1985 <i>Mechanical and climatic tests methods</i> [Identical]
QC 001002	BS QC 001002: <i>Rules of Procedure of the IEC Quality Assessment System for Electronic Components</i> [IECQ] [Identical]

^a Undated in the text

A British Standard does not purport to include all the necessary provisions of a contract. Users of British Standards are responsible for their correct application.

Compliance with a British Standard does not of itself confer immunity from legal obligations.

Summary of pages

This document comprises a front cover, an inside front cover, pages i to iv, pages 1 to 11 and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

